

10/577114

PATENT

Attorney Docket No. 536-009.026

1AP20 Rec'd PCT/PTO 24 APR 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of: :
Hans GUSTAT : Intl. Application No.: **PCT/EP2004/012351**
Serial No.: **To be assigned** : Intl. Filing Date: **October 28, 2004**
Filed: **Herewith** : Priority Date: **October 31, 2003**
For: **Processor component**

Commissioner for Patents
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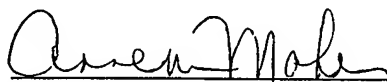
INFORMATION DISCLOSURE STATEMENT

Sir:

Applicants submit herewith references of which they are aware, which they believe may be material to the examination of this application and in respect of which they may have a duty to disclose in accordance with 37 CFR §1.56.

While this Information Disclosure Statement (IDS) may be "material" pursuant to 37 CFR §1.56(b), it is not intended to constitute an admission that any document referred to herein is "prior art" for this invention unless specifically designated as such.

I hereby certify that this correspondence is being deposited with the United States Postal Service on this date, April 24, 2006, in an envelope marked as, and with sufficient postage as, "Express Mail - Post Office to Addressee," Mailing Label No. EV 711307825 US, addressed to the Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450.


Annemarie Maher

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In accordance with 37 CFR §1.97(g), the filing of this IDS shall not be construed to mean that a search has been made or that no other material information as defined under 37 CFR §1.56(a) exists.

Enclosed is an International Search Report issued in International Patent Application No. PCT/EP2004/012351 filed on October 28, 2004, from which application the applicant now requests entry into the US national stage. Also enclosed is a Form PTO-1449 listing the cited references. The abstract of each reference provides a concise explanation thereof.

This IDS is being submitted simultaneously with the request for entry into the US national stage in this matter; therefore, the undersigned respectfully submits that no fee is due for filing this IDS. If any fee is due, the Commissioner is hereby authorized to charge to deposit account 23-0442 any fee deficiency required to submit this IDS.

Respectfully submitted,



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Dated: April 24, 2006

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FORM PTO-1449 INFORMATION DISCLOSURE STATEMENT			ATTY DOCKET NO. 536-009.026		SERIAL NO. To be assigned 10/577114		
			APPLICANT: Hans GUSTAT				
			FILING DATE: Herewith		ART UNIT: To be assigned		
UNITED STATES PATENT DOCUMENTS							
EXAM. INITIAL		DOCUMENT NUMBER	DATE	INVENTOR/ASSIGNEE	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		6,500,696	Dec. 31, 2002	Sutherland			
		6,496,889	Dec. 17, 2002	Perino et al.			
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		5,786,979	July 28, 1998	Douglass			
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES/NO
		WO 2004/012265	Feb. 05, 2004	PCT/WIPO			
OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)							
	1	T. Mangold et al., "A multichip module integration technology on silicon substrate for high frequency applications," 4 pages.					
	2	N. Rinaldi et al., "U.C.A.N.'s ultra wide band system: baseband algorithm design," April 2003, 6 pages.					
	3	O. Albert et al., "Low-power ultra-wideband radio testbed for short-range data transmission," 6 pages.					
	4	N. M. Khan et al., "Use of state-space approach and Kalman filter estimation in channel modeling for multiuser detection in time-varying environment," 5 pages.					
	6	A. L. Sigvartsen, "Inside the AMD Hammer microprocessor - AMD's next generation microprocessor architecture (Fred Weber)," October 22, 2001, infosatellite.com/news, 15 pages.					
	6	D. Salzman et al., "Manufacturability of capacitively coupled multichip modules," IEEE Transactions on Components, Packaging and Manufacturing Technology - Part B, Vol. 18, No. 2, May 1995, pp.277-281.					
	7	D. Salzman et al., "Application of capacitive coupling to switch fabrics," IEEE 1994, pp.195-199.					
Examiner (To be assigned)				Date:			

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FORM PTO-1449 INFORMATION DISCLOSURE STATEMENT		ATTY DOCKET NO. 536-009.026		SERIAL NO. 10/577114 To be assigned			
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		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES/NO
OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)							
	8	D. Salzman et al., "Capacitively coupled multichip modules," MCM '94 Proceedings, pp.487-494.					
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	14	R. J. Drost et al., "Proximity communication," IEEE 2003 Custom Integrated Circuits Conference, pp.469-472.					
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	16	K. Kanda et al., "1.27 Gb/s/pin 3mW/pin wireless superconnect (WSC) interface scheme," ISSCC 2003/Session 10/High Speed Building Blocks/Paper 10.7, IEEE 2003 International Solid-State Circuits Conference, 10 pages.					
Examiner (To be assigned)				Date:			